

L Number	Hits	Search Text	DB	Time stamp
1	5	(semiconductor near4 (surface adj treatment)) and (inversion adj condition)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/06/23 15:02
2	21	(semiconductor near4 (surface adj treatment)) and (electron adj hole)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/06/23 15:02
3	11	(semiconductor near4 (surface adj treatment)) and (electron adj hole adj pair)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/06/23 15:03
4	6	((semiconductor near4 (surface adj treatment)) and (electron adj hole adj pair)) and (IR or infrared)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/06/23 15:04
-	609	semiconductor near4 (surface adj treatment)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/06/22 14:45
-	661	semiconductor near4 (surface adj treatment)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/06/23 15:02
-	308	(semiconductor near4 (surface adj treatment)) and wafer	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/06/22 14:45
-	3	((semiconductor near4 (surface adj treatment)) and wafer) and (inversion adj condition)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/06/23 15:01
-	3	((semiconductor near4 (surface adj treatment)) and wafer) and (IR or infrared) and (inversion adj condition)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/06/23 11:53
-	4	((semiconductor near4 (surface adj treatment)) and wafer) and (IR or infrared)) and (desorb or desorption)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/06/23 11:51
-	7	("3850508" "4824698" "5216362" "5581194" "5977788" "616685PA163262207D04" "616685PA163262207D04)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/06/23 11:52
-	3	((semiconductor near4 (surface adj treatment)) and (IR or infrared)) and (inversion adj condition)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/06/23 11:54
-	5	(semiconductor near4 (surface adj treatment)) and (inversion adj condition)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/06/23 12:28
-	28	((semiconductor near4 (surface adj treatment)) and wafer) and (IR or infrared)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/06/23 15:03
-	5	(semiconductor near6 (surface adj treatment)) and (inversion adj condition)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/06/23 13:03